

Microsemi Scottsdale

Material Declaration

<u>Parts Number</u>	<u>Package</u>	<u>Package Total Mass in grams (g).</u>				
SMAe3	DO-214AC	0.064				
<u>Component Description</u>	<u>Material Name</u>	<u>Weight in grams</u>	<u>Substance Name</u>	<u>CAS Number</u>	<u>Weight in grams</u>	<u>percent</u>
Molded Body	Epoxy	0.0322	Silica Crystall	60676-86-0	0.024472	76.000
			Epoxy Resin	129915-35-1	0.0047656	14.800
			Bromine-Epoxy Resin	40039-93-8	0.000322	1.000
			Phenol Resin	26834-02-6	0.002254	7.000
			Antimony Trioxide	1309-64-4	0.000322	1.000
			Carbon Black	1333-86-4	0.0000644	0.200
Lead Frame	Copper	0.0267	Copper	7440-50-8	0.0267	100.000
Solder Disc	Preforms	0.00256	Lead	7439-92-1	0.002368	92.500
			Silver	7440-22-4	0.000128	5.000
			Tin	7440-31-5	0.000064	2.500
Diode Dice	Silicon	0.0019	Silicon	7440-21-3	0.0019	100.000
Plating	Tin	0.00064	Tin	7440-31-5	0.00064	100.000
					0.064	